

PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
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DATE SIGNED:	07/19/2022
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ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	(City and State OR Country)
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Chee Hiong CHEW	Seremban, Malaysia
Soon Wei WANG	Seremban, Malaysia
Eiji KUROSE	Oizumi-machi, Japan

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: SEMICONDUCTOR PACKAGES WITH THIN DIE AND RELATED METHODS

Attorney Docket No.: ONS02401P05US

Serial No.: 16/879,251

Filing Date: May 20, 2020

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

譲渡及び契約書

適正・相当な対価を受領しており、それが十分な対価であることを認めた上で、我々こと

(市及び州又は国)	の(氏名)
Francis J. CARNEY	Mesa, Arizona, U.S.A.
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所有権: SEMICONDUCTOR PACKAGES WITH THIN DIE AND RELATED METHODS

代理人明細書番号: ONS02401P05US

シリアル番号: 16/879,251

申請日: May 20, 2020

これには、上記にリストされた申請、及び全ての仮の、非仮の、分割の、継続の、一部継続の、国際の、外国の申請、及びそれに関連するその他の申請に対する全ての権利、所有権、利益に加え、前述のいずれの許諾、発行、特許証、再発行、再審査、更新、優先権、優先権の主張及び前述のいずれの侵害のため過去の損害賠償を得る権利全て（以下「特許権」）を含んでいる。

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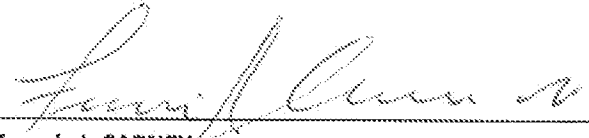
We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

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By (Inventor signature):


Francis J. CARNEY

Signed on this 18 day of MAY, 2020
day month year

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By (Inventor signature):  _____
Chee Hiong CHEW

Signed on this 12 day of May, 2020
day month year

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By (Inventor signature): Wang
Soon Wei WANG

Signed on this 12 day of May, 2020
day month year

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By (Inventor signature):

署名欄 (発明者の署名):

Eiji KUROSE
Eiji KUROSE

認証日:

May 10 2020